3D Semiconductor Packaging Market by Technology (3D Through silicon via, 3D Package on Package, 3D Fan Out Based, 3D Wire Bonded),by Material (Organic Substrate, Bonding Wire, Leadframe, Encapsulation Resin, Ceramic Package, Die Attach Material),by Industry vertical (Electronics, Industrial, Automotive & Transport, Healthcare, IT & Telecommunication, Aerospace & Defense)- Global Opportunity Analysis and Industry Forecast, 2014-2022

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Abstracts

Global 3D semiconductor packaging market size is expected to garner $8.9 billion by 2022, growing at a CAGR of 15.7% from 2016 to 2022. 3D semiconductor packaging refers to an advanced packaging technology of semiconductor chips in which two or more layers of active electronic components are stacked together and interconnected vertically as well as horizontally to perform as a single device. This technology possesses various advantages over other advanced packaging technologies such as reduced space consumption, decreased power loss, better overall performance, and enhanced efficiency.

A special feature of 3D packaging design that distinguishes it from other advanced packaging methods is that it mounts the die on top of each other unlike side-by-side mounting of 2D packaging, which consecutively acquires less space, and results in the formation of more compact chips and aids the growing demand for circuit miniaturization. Furthermore, overall less cost of as compared to other advanced packaging technology options gives an edge and fuels its adoption in memory chip stacking, I/O DRAMS, and high bandwidth applications. The need for miniaturization of memory chips, high bandwidth requirements in electronic circuits, and reduced cost

than other advanced packaging technologies are prime factors, which foster the demand in 3D packaging industry.

The need to control the chip designing cost, which plays a major role in overall price of electronic devices; increase in demand for miniaturized circuits; and short replacement period of electronics products, which are constituted of integrated circuits manufactured with 3D packaging technology are the major factors that drive the growth in the 3D semiconductor packaging industry. However, high cost required to establish a 3D semiconductor packaging facility hinders the growth opportunities in 3D semiconductor packaging industry and this is anticipated to grow the overall 3D semiconductor packaging market size to three folds of the current value. On the contrary, the growth in trend of Internet of Things (IoT) and increase in number of wireless devices are opening new opportunities which will increase 3D semiconductor packaging market share in overall advanced packaging market. The ongoing 3D semiconductor packaging market trends suggest that the market will witness a double-digit growth in next five to six years.

The global 3D semiconductor packaging market is segmented on the basis of technology, materials, industry vertical, and geography. Based on technology, the 3D semiconductor packaging industry is segmented into 3D through silicon via, 3D package on package, 3D fan out based, 3D wire bonded, and others. By materials, the 3D semiconductor packaging market is classified into organic substrate, bonding wire, leadframe, encapsulation resin, ceramic package, die attach material, and others Furthermore, the 3D semiconductor packaging industry is categorized on the basis of industry vertical, which includes electronics, industrial, automotive & transport, healthcare, IT & telecommunication, aerospace & defense, and others. Geographically, it is divided into North America, Europe, Asia-Pacific, and LAMEA.

The key players profiled in the report include Amkor Technology, ASE group, Siliconware Precision Industries Co., Ltd., Jiangsu Changjiang Electronics Technology Co. Ltd., S?SS MicroTec AG., International Business Machines Corporation (IBM), Intel Corporation, Qualcomm Technologies, Inc., STMicroelectronics, and Taiwan Semiconductor Manufacturing Company.

POTENTIAL BENEFITS FOR STAKEHOLDERS:

This report provides an in-depth analysis of the global 3D semiconductor packaging market along with current 3D semiconductor packaging market trends and future estimations to identify lucrative investment opportunities

This report identifies the key drivers, opportunities, and restraints that shape the market along with their impact analysis

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Porter's Five Forces analysis highlights the potency of buyers and suppliers that participate in this market to facilitate better business decisions for stakeholders and strengthen their supplier and buyer networks

Market estimation of geographical regions is based on the current market scenario and future trends.

MARKET SEGMENTATION

The market is segmented on the basis of technology, materials, industry vertical, and geography.
BY TECHNOLOGY

3D Through Silicon Via

3D Package on Package

3D Fan Out Based

3D Wire Bonded

Others (Flip Chip and Hybrid)

BY MATERIAL

Organic Substrate

Bonding Wire

Leadframe

Encapsulation Resins

Ceramic Packages

Die Attach Material

Others (Underfill Materials and Solder Balls)

BY INDUSTRY VERTICAL

Electronics

Industrial

Automotive & Transport

Healthcare

IT & Telecommunication

Aerospace & Defense

Others (Media & Entertainment and Renewable Energy Resources)

BY GEOGRAPHY

North America

U.S.

Canada

Mexico

Europe

UK

Germany

France

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Italy

Rest of Europe

Asia-Pacific

China

Japan

Taiwan

South Korea

India

Rest of Asia-Pacific

LAMEA

Latin America

Middle East

Africa

KEY PLAYERS

Amkor Technology

ASE Group

Siliconware Precision Industries Co., Ltd.

Jiangsu Changjiang Electronics Technology Co. Ltd.

S?SS MicroTec AG.

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International Business Machines Corporation (IBM)

Intel Corporation

Qualcomm Technologies, Inc.

STMicroelectronics

Taiwan Semiconductor Manufacturing Company

Other players in the value chain include (profiles not included in the report)

Sony corp.

SAMSUNG electronics co. ltd.

Advanced Micro Devices, Inc.

Cisco

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